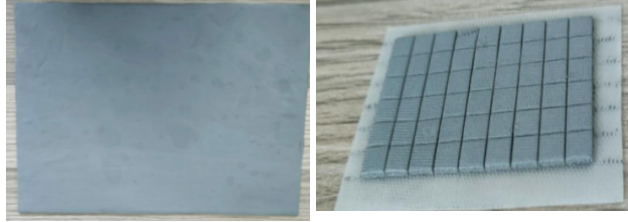


Data Sheet Of Thermal Pad-TSP600-K120

Characteristic:

- Thermal conductivity=12W/mk or customized
- Excellent adhesion and low hardness
- Electrical insulation
- Excellent softness



The TSP600-K120 series is a new and high-performance thermal conductive gap filling material. In addition to high thermal conductivity, TSP600-K120, when combined with heat sinks or other heating elements, will fully disperse on the surface, allowing the product to achieve optimal results.

Properties	Typical Data	Test Method
Color	Grey Or Customized	Visual
Thickness(mm)	1~5	ASTM D374
Density (g/cc)	3.5	ASTM D792
Hardness(Shore C)	30	ASTM D2240
Tear Strength(N/mm)	0.26	ASTM D624
Tensile Strength (Psi)	8.2	ASTM D412
Elongation(%)	10	ASTM D412
Continuous Use Temperature(°C)	-40-150	-
Electrical Properties		
Dielectric Breakdown Voltage(KV/AC)	6	ASTM D149
Dielectric Constant (1000 HZ)	6	ASTM D150
Volume Resistivity(ohm-meter)	10 ¹¹	ASTM D257
UL Flammability Rating	94 V-0	UL
Thermal Properties		
Thermal Conductivity(W/m-k)	12±0.5	ASTM D5470

Product testing thickness of 1mm sample.

Storage under dark conditions, temperature ≤ 40 ° C, humidity ≤ 70%, Stacked no more than 7 layers, with a total height of less than 1 meter, quality guarantee 1 year

Typical Applications

1. Large scale communication equipment and peripheral supporting equipment;
2. Computers, tablets computers, smart phones:
3. Various radiators, solar power DC-AV inverters

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